

WHAT IS CLAIMED IS:

1. A liquid cooling system comprising:

a housing;

a receptacle disposed in the housing, the receptacle capable of mating with packaging material associated with a processor to form a cavity, the processor generating heat;

an inlet disposed in the housing, the inlet receiving liquid, the liquid flowing through the cavity and removing the heat by flowing across the packaging material; and

an outlet disposed in the housing, the outlet providing an exit point for the liquid flowing through the cavity.

2. A liquid cooling system as set forth in claim 1, further comprising,

a first conduit coupled to the outlet, the first conduit transporting heated liquid in response to the liquid flowing through the cavity;

a heat exchange system coupled to the first conduit, the heat exchange system receiving the heated liquid transported on the first conduit and generating cooled liquid; and

a second conduit coupled to the inlet and coupled to the heat exchange system, the inlet receiving the liquid in response to transporting the cooled liquid on the second conduit.

3. A liquid cooling system as set forth in claim 2, wherein the inlet is positioned below the outlet.

4. A liquid cooling system as set forth in claim 2, wherein an input cavity is disposed in the heat exchange system, the input cavity receiving the heated liquid.

5. A liquid cooling system as set forth in claim 2, wherein a dissipater is disposed in the heat exchange system, the dissipater generating the cooled liquid in response to receiving the heated liquid.

6. A liquid cooling system as set forth in claim 2, wherein an output cavity is disposed in the heat exchange system, the output cavity receiving the cooled liquid.

7. A liquid cooling system as set forth in claim 6, wherein a pump is disposed in the output cavity, the pump pumping the cooled liquid, wherein the step of transporting the cooled liquid on the second conduit is performed in response to the pump pumping the cooled liquid.

8. A liquid cooling system as set forth in claim 1, wherein the liquid cooling system is disposed in a casing, the liquid cooling system further comprising a heat exchange system including a heat dissipater in liquid communication with the outlet;

a liquid cavity in liquid communication with the heat dissipater for storing cooled liquid; and

a pump disposed within the liquid cavity for circulating the liquid through the liquid cooling system.

9. A liquid cooling system as set forth in claim 8, further comprising an airflow device for directing air from within the casing over the heat dissipater and out of the casing.

10. A liquid cooling system as set forth in claim 1, further comprising,
a first conduit coupled to the outlet, the first conduit transporting heated liquid in response to the liquid flowing through the cavity;

a heat exchange system coupled to the first conduit, the heat exchange system further comprising, a heat dissipater generating cooled liquid in response to receiving the heated liquid, a liquid cavity housing the cooled liquid, and a fan positioned between a heat dissipater and the liquid cavity, the fan causing air flow over the heat dissipater and the liquid cavity; and

a second conduit coupled to the inlet and coupled to the liquid cavity, the inlet receiving the cooled liquid in response to transporting the cooled liquid on the second conduit.

11. A liquid cooling system as set forth in claim 10, wherein the heat dissipater further comprises a liquid tube positioned within the heat dissipater, the liquid tube conveying the heated liquid through the heat dissipater to generate the cooled liquid.

12. A liquid cooling system as set forth in claim 10, further comprising a pump coupled to the liquid cavity, the pump enabling the step of transporting the cooled liquid on the second conduit.

13. A liquid cooling system comprising:

a housing;

a receptacle disposed in the housing, the receptacle capable of mating with packaging material associated with a processor to form a cavity, the processor generating heat;

a pump disposed in the cavity and pumping liquid through the cavity, the liquid flowing through the cavity and removing the heat by making contact with the packaging material in response to the pump pumping liquid through the cavity;

an inlet disposed in the housing, the inlet receiving the liquid in response to the pump pumping the liquid through the cavity; and

an outlet disposed in the housing, the outlet outputting the liquid in response to the pump pumping the liquid through the cavity.

14. Liquid cooling system as set forth in claim 13, further comprising, a first conduit coupled to the outlet, the first conduit transporting heated liquid in response to pumping liquid through the cavity;

a heat exchange system coupled to the first conduit, the heat exchange system receiving the heated liquid transported on the first conduit and generating cooled liquid; and

a second conduit coupled to the inlet and coupled to the heat exchange system, the inlet receiving the liquid in response to transporting the cooled liquid on the second conduit and in response to pumping the liquid through the cavity.

15. A liquid cooling system as set forth in claim 13, wherein the inlet is positioned below the outlet.

16. A liquid cooling system as set forth in claim 14, wherein an input cavity is disposed in the heat exchange system, the input cavity receiving the heated liquid.

17. A liquid cooling system as set forth in claim 14, wherein a dissipater is disposed in the heat exchange system, the dissipater generating the cooled liquid in response to receiving the heated liquid.

18. A liquid cooling system as set forth in claim 14, wherein an output cavity is disposed in the heat exchange system, the output cavity receiving the cooled liquid.

19. A liquid cooling system as set forth in claim 18, wherein a second pump is disposed in the output cavity, the second pump pumping the cooled liquid, wherein the step of transporting the cooled liquid on the second conduit is performed in response to the second pump pumping the cooled liquid.

20. A liquid cooling system as set forth in claim 13, wherein the liquid cooling system is disposed in a casing, the liquid cooling system further comprising a heat exchange system including a heat dissipater in liquid communication with the outlet and configured to receive liquid from the outlet;

a liquid cavity in liquid communication with the heat dissipater for storing cooled liquid; and

a second pump disposed within the liquid cavity, the second pump further circulating liquid through the system.

21. A liquid cooling system as set forth in claim 20, further comprising an airflow device for directing air over the heat dissipater and out of the casing.

22. A liquid cooling system as set forth in claim 13, further comprising, a first conduit coupled to the outlet, the first conduit transporting heated liquid in response to the liquid flowing through the cavity;

a heat exchange system coupled to the first conduit, the heat exchange system further comprising, a heat dissipater generating cooled liquid in response to receiving the heated liquid, a liquid cavity housing the cooled liquid, and a fan positioned between the heat dissipater and the liquid cavity the fan causing air flow over the heat dissipater and the liquid cavity; and

a second conduit coupled to the inlet and coupled to the liquid cavity, the inlet receiving the liquid in response to transporting the cooled liquid on the second conduit.

23. A liquid cooling system as set forth in claim 22, wherein the heat dissipater further comprises a liquid tube positioned within the heat dissipater, the liquid tube conveying the heated liquid through the heat dissipater to generate the cooled liquid.

24. A liquid cooling system as set forth in claim 22, further comprising a second pump coupled to the liquid cavity, the second pump pumping liquid through the liquid cavity.

25. A liquid cooling system as set forth in claim 13, further comprising, a first conduit coupled to the outlet, the first conduit transporting heated liquid in response to pumping liquid through the cavity;

a heat exchange system coupled to the first conduit, the heat exchange system further comprising, a heat dissipater generating cooled liquid in response to receiving the heated liquid and a fan positioned to cause air flow over the heat dissipater; and

a second conduit coupled to the inlet, the inlet receiving the liquid in response to transporting the cooled liquid on the second conduit.

26. A liquid cooling system as set forth in claim 25, wherein the heat dissipater further comprises a liquid tube positioned within the heat dissipater, the liquid tube conveying the heated liquid through the heat dissipater to generate the cooled liquid.

27. A liquid cooling system as set forth in claim 25, wherein the heat dissipater further comprises at least one liquid tube positioned within the heat dissipater and fins positioned within the heat dissipater, the fan positioned to cause the air flow over the at least one liquid tube and over the fins.

28. A liquid cooling system comprising:

a first conduit transporting first liquid;

a first heat transfer system coupled to the first conduit and capable of mating with a processor on a first side, the processor generating heat, the first heat transfer system capable of dissipating the heat by conveying the first liquid through the first heat transfer system;

a second heat transfer system coupled to the first conduit and capable of mating with the processor on a second side, the second heat transfer system capable of further dissipating the heat by conveying the first liquid through the second heat transfer system; and

a second conduit coupled to the first heat transfer system and coupled to the second heat transfer system, the second conduit transporting second liquid in response to conveying the first liquid through the first heat transfer system and in response to conveying first liquid through the second heat transfer system.

29. A liquid cooling system as set forth in claim 28, further comprising,

a heat exchange system coupled to the first conduit and coupled to the second conduit, the heat exchange system generating cooled liquid in response to the second liquid transported on the second conduit, the first conduit transporting the first liquid in response to the cooled liquid.

30. A liquid cooling system as set forth in claim 29, wherein an input cavity is disposed in the heat exchange system, the input cavity receiving the second liquid.

31. A liquid cooling system as set forth in claim 29, wherein a dissipater is disposed in the heat exchange system, the dissipater generating the cooled liquid in response to receiving the second liquid.

32. A liquid cooling system as set forth in claim 29, wherein an output cavity is disposed in the heat exchange system, the output cavity receiving the cooled liquid.

33. A liquid cooling system as set forth in claim 32, wherein a pump is disposed in the output cavity, the pump pumping the cooled liquid.

34. A liquid cooling system as set forth in claim 28, wherein the liquid cooling system is disposed in a casing, the liquid cooling system further comprising a heat exchange system including a heat dissipater in liquid communication with the second conduit;

a liquid cavity in liquid communication with the heat dissipater, the liquid cavity storing liquid; and

a pump disposed within the liquid cavity, the pump circulating liquid through the system.

35. A liquid cooling system as set forth in claim 34, further comprising an airflow device positioned to direct air over the heat dissipater and out of the casing.

36. A liquid cooling system as set forth in claim 28, further comprising, a heat exchange system coupled to the second conduit, the heat exchange system further comprising, a heat dissipater generating cooled liquid in response to receiving the second liquid, a liquid cavity housing the first liquid in response to receiving the second liquid, and a fan positioned between the heat dissipater and the liquid cavity the fan causing air flow over the heat dissipater and the liquid cavity.

37. A liquid cooling system as set forth in claim 36, wherein the heat dissipater further comprises a liquid tube positioned within the heat dissipater,

the liquid tube conveying the second liquid through the heat dissipater to generate the second liquid.

38. A liquid cooling system as set forth in claim 36, further comprising a pump coupled to the liquid cavity, the pump generating the first liquid.

39. A liquid cooling system comprising:

- a first housing comprising a receptacle capable of mating with first packaging material associated with a processor, to form a first cavity, the processor generating heat;

- a second housing comprising a receptacle capable of mating with second packaging material associated with the processor, to form a second cavity;

- a first inlet disposed in the first housing, the first inlet receiving first liquid, the first liquid flowing through the first cavity and removing the heat by making contact with the first packaging material;

- a second inlet disposed in the second housing, the second inlet receiving second liquid, the second liquid flowing through the second cavity and removing the heat by making contact with the second packaging material;

- a first outlet disposed in the first housing, the first outlet providing and exit point for the first liquid flowing through the first cavity; and

- a second outlet disposed in the second housing, the second outlet providing and exit point for the second liquid flowing through the second cavity.

40. A liquid cooling system as set forth in claim 39, further comprising,

- a first conduit coupled to the first outlet and coupled to the second outlet, the first conduit transporting heated liquid in response to the first liquid flowing through the first cavity and in response to the second liquid flowing through the second cavity;

a heat exchange system coupled to the first conduit, the heat exchange system receiving the heated liquid transported on the first conduit and generating cooled liquid; and

a second conduit coupled to the first inlet, coupled to the second inlet and coupled to the heat exchange system, the first inlet receiving the cooled liquid in response to transporting the cooled liquid on the second conduit and the first inlet receiving the cooled liquid in response to transporting the cooled liquid on the second conduit.

41. A liquid cooling system as set forth in claim 39, wherein the first inlet is positioned below the first outlet.

42. A liquid cooling system as set forth in claim 40, wherein an input cavity is disposed in the heat exchange system, the input cavity receiving the heated liquid.

43. A liquid cooling system as set forth in claim 40, wherein a dissipater is disposed in the heat exchange system, the dissipater generating the cooled liquid in response to receiving the heated liquid.

44. A liquid cooling system as set forth in claim 40, wherein an output cavity is disposed in the heat exchange system, the output cavity receiving the cooled liquid.

45. A liquid cooling system as set forth in claim 44, wherein a pump is disposed in the output cavity, the pump pumping the cooled liquid, wherein the step of transporting the cooled liquid on the second conduit is performed in response to the pump pumping the cooled liquid.

46. A liquid cooling system as set forth in claim 39, wherein the liquid cooling system is disposed in a casing, the liquid cooling system further comprising a heat exchange system including a heat dissipater in liquid communication with the first outlet and with the second outlet;

a liquid cavity in liquid communication with the heat dissipater for storing cooled liquid; and

a pump disposed within the liquid cavity for circulating liquid through the system.

47. A liquid cooling system as set forth in claim 46, further comprising an airflow device for directing air over the heat dissipater and out of the casing.

48. A liquid cooling system as set forth in claim 39, further comprising, a first conduit coupled to the first outlet and coupled to the second outlet, the first conduit transporting heated liquid in response to the liquid flowing through the first cavity and in response to the liquid flowing through the second cavity;

a heat exchange system coupled to the first conduit, the heat exchange system further comprising, a heat dissipater generating cooled liquid in response to receiving the heated liquid, a liquid cavity housing cooled liquid, and a fan positioned between the heat dissipater and the liquid cavity the fan causing air flow over the heat dissipater and the liquid cavity; and

a second conduit coupled to the first inlet, coupled to the second inlet and coupled to the liquid cavity, the first inlet receiving the cooled liquid in response to transporting the cooled liquid on the second conduit and the second inlet receiving the cooled liquid in response to transporting the cooled liquid on the second conduit.

49. A liquid cooling system as set forth in claim 48, wherein the heat dissipater further comprises a liquid tube positioned within the heat dissipater, the liquid tube conveying the heated liquid through the heat dissipater to generate the cooled liquid.

50. A liquid cooling system as set forth in claim 48, further comprising a pump coupled to the liquid cavity, the pump performing the step of transporting the cooled liquid on the second conduit.

51. A liquid cooling system comprising:

a first conduit transporting first liquid;

a first heat transfer system coupled to the first conduit and capable of mating with a first processor on a first side, the first processor generating first heat, the first heat transfer system capable of dissipating the first heat by conveying the first liquid through the first heat transfer system;

a second heat transfer system coupled to the first conduit and capable of mating with the first processor on a second side and a second processor on a first side, the second heat transfer system capable of further dissipating the first heat by conveying the first liquid through the second heat transfer system and the second heat transfer system capable of dissipating the second heat by conveying the first liquid through the second heat transfer system;

a third heat transfer system coupled to the first conduit and capable of mating with the second processor on a second side, the third heat transfer system capable of further dissipating the second heat by conveying the first liquid through the third heat transfer system; and

a second conduit coupled to the first heat transfer system, coupled to the second heat transfer system and coupled to the third heat transfer system, the second conduit transporting second liquid in response to conveying the first liquid through the first heat transfer system, in response to conveying first liquid through the second heat transfer system and in response to conveying first liquid through the third heat transfer system.

52. A liquid cooling system as set forth in claim 51, further comprising, a heat exchange system coupled to the first conduit and coupled to the second conduit, the heat exchange system generating cooled liquid in response to the second liquid transported on the second conduit, the first conduit transporting the first liquid in response to the cooled liquid.

53. A liquid cooling system as set forth in claim 52, wherein an input cavity is disposed in the heat exchange system, the input cavity receiving the second liquid.

54. A liquid cooling system as set forth in claim 52, wherein a dissipater is disposed in the heat exchange system, the dissipater generating the cooled liquid in response to receiving the second liquid.

55. A liquid cooling system as set forth in claim 52, wherein an output cavity is disposed in the heat exchange system, the output cavity receiving the cooled liquid.

56. A liquid cooling system as set forth in claim 55, wherein a pump is disposed in the output cavity, the pump pumping the cooled liquid.

57. A liquid cooling system as set forth in claim 51, wherein the liquid cooling system is disposed in a casing, the liquid cooling system further comprising a heat exchange system including a heat dissipater in liquid communication with the first conduit and the second conduit;

a liquid cavity in liquid communication with the heat dissipater, the liquid cavity storing liquid; and

a pump disposed within the liquid cavity, the pump circulating liquid through the system.

58. A liquid cooling system as set forth in claim 57, further comprising an airflow device for directing air over the heat dissipater and out of the casing.

59. A liquid cooling system as set forth in claim 51, further comprising, a heat exchange system coupled to the second conduit, the heat exchange system further comprising, a heat dissipater generating cooled liquid in response to receiving the first liquid, a liquid cavity housing second liquid in response to receiving the first liquid, and a fan positioned between the heat dissipater and the liquid cavity the fan causing air flow over the heat dissipater and the liquid cavity.

60. A liquid cooling system as set forth in claim 59, wherein the heat dissipater further comprises a liquid tube positioned within the heat dissipater, the liquid tube conveying the first liquid through the heat dissipater to generate the second liquid.

61. A liquid cooling system as set forth in claim 59, further comprising a pump coupled to the liquid cavity, the pump generating the first liquid.

62. A liquid cooling system comprising:
a first housing comprising a first receptacle capable of mating with first packaging material associated with a first processor, to form a first cavity, the first processor generating first heat;
a second housing comprising a second receptacle capable of mating with second packaging material associated with the first processor and comprising a third receptacle capable of mating with third packaging material associated with a second processor, to form a second cavity, the second processor generating second heat;

a third housing comprising a fourth receptacle capable of mating with fourth packaging material associated with the second processor, to form a third cavity;

a first inlet disposed in the first housing, the first inlet receiving first liquid, the first liquid flowing through the first cavity and dissipating the first heat by making contact with the first packaging material;

a second inlet disposed in the second housing, the second inlet receiving second liquid, the second liquid flowing through the second cavity and dissipating the first heat by making contact with the second packaging material, the second liquid flowing through the second cavity and dissipating the second heat by making contact with the second packaging material;

a third inlet disposed in the third housing, the third inlet receiving third liquid, the third liquid flowing through the third cavity and removing the second heat by making contact with the fourth packaging material;

a first outlet disposed in the first housing, the first outlet providing and exit point for the first liquid flowing through the first cavity;

a second outlet disposed in the second housing, the second outlet providing and exit point for the second liquid flowing through the second cavity; and

a third outlet disposed in the third housing, the third outlet providing and exit point for the third liquid flowing through the third cavity.

63. A liquid cooling system as set forth in claim 62, further comprising,

a first conduit coupled to the first outlet, coupled to the second outlet and coupled to the third outlet, the first conduit transporting heated liquid in response to the liquid flowing through the first cavity, in response to the liquid flowing through the second cavity and in response to the liquid flowing through the third cavity;

a heat exchange system coupled to the first conduit, the heat exchange system receiving the heated liquid transported on the first conduit and generating cooled liquid; and

a second conduit coupled to the first inlet, coupled to the second inlet, coupled to the third inlet and coupled to the heat exchange system, the first inlet receiving the cooled liquid in response to transporting the cooled liquid on the second conduit, the second inlet receiving the cooled liquid in response to transporting the cooled liquid on the second conduit and the third inlet receiving the cooled liquid in response to transporting the cooled liquid on the second conduit.

64. A liquid cooling system as set forth in claim 62, wherein the third inlet is positioned below the third outlet.

65. A liquid cooling system as set forth in claim 63, wherein an input cavity is disposed in the heat exchange system, the input cavity receiving the heated liquid.

66. A liquid cooling system as set forth in claim 63, wherein a dissipater is disposed in the heat exchange system, the dissipater generating the cooled liquid in response to receiving the heated liquid.

67. A liquid cooling system as set forth in claim 63, wherein an output cavity is disposed in the heat exchange system, the output cavity receiving the cooled liquid.

68. A liquid cooling system as set forth in claim 67, wherein a pump is disposed in the output cavity, the pump pumping the cooled liquid, wherein the step of transporting the cooled liquid on the second conduit is performed in response to the pump pumping the cooled liquid.

69. A liquid cooling system as set forth in claim 62, wherein the liquid cooling system is disposed in a casing, the liquid cooling system further comprising a heat exchange system including a heat dissipater in liquid communication with the first outlet, the second outlet and the third outlet;

a liquid cavity in liquid communication with the heat dissipater for storing cooled liquid; and

a pump disposed within the liquid cavity for circulating liquid through the system.

70. A liquid cooling system as set forth in claim 69, further comprising an airflow device for directing air over the heat dissipater and out of the casing.

71. A liquid cooling system as set forth in claim 62, further comprising, a first conduit coupled to the first outlet, coupled to the second outlet, and the third outlet the first conduit transporting heated liquid in response to the liquid flowing through the first cavity, in response to the liquid flowing through the second cavity and in response to the liquid flowing through the third cavity;

a heat exchange system coupled to the first conduit, the heat exchange system further comprising, a heat dissipater generating cooled liquid in response to receiving the heated liquid, a liquid cavity housing the cooled liquid, and a fan positioned between the heat dissipater and the liquid cavity the fan causing air flow over the heat dissipater and the liquid cavity; and

a second conduit coupled to the first inlet, coupled to the second inlet and coupled to the liquid cavity, the first inlet receiving the cooled liquid in response to transporting the cooled liquid on the second conduit, the second inlet receiving the cooled liquid in response to transporting the cooled liquid

on the second conduit and the third inlet receiving the cooled liquid in response to transporting the cooled liquid on the second conduit.

72. A liquid cooling system as set forth in claim 71, wherein the heat dissipater further comprises a liquid tube positioned within the heat dissipater, the liquid tube conveying the heated liquid through the heat dissipater to generate the cooled liquid.

73. A liquid cooling system as set forth in claim 71, further comprising a pump coupled to the liquid cavity, the pump performing the step of transporting the cooled liquid on the second conduit.

74. A liquid cooling system comprising:
a first conduit transporting liquid;
a cavity coupled to the first conduit, the cavity mating with packaging material deployed on multiple sides of a processor, the processor generating heat, the cavity conveying the liquid in response to transporting the liquid on the first conduit, the liquid dissipating the heat; and
a second conduit coupled to the cavity, the second conduit transporting liquid in response to the cavity conveying the liquid.

75. A liquid cooling system as set forth in claim 74, wherein the liquid is in direct contact with the packaging material during the step of the cavity conveying the liquid.

76. A liquid cooling system as set forth in claim 74, wherein the liquid cooling system is disposed in a casing, the liquid cooling system further comprising a heat exchange system including a heat dissipater in liquid communication with the first conduit;
a liquid cavity in liquid communication with the heat dissipater for storing cooled liquid; and

a pump disposed within the liquid cavity for circulating liquid through the system.

77. A liquid cooling system as set forth in claim 74, further comprising, a heat exchange system coupled to the second conduit, the heat exchange system receiving the liquid transported on the second conduit and generating cooled liquid.

78. A liquid cooling system as set forth in claim 77, wherein an input cavity is disposed in the heat exchange system, the input cavity receiving the liquid transported on the second conduit.

79. A liquid cooling system as set forth in claim 77, wherein a dissipater is disposed in the heat exchange system, the dissipater generating cooled liquid in response to receiving the liquid transported on the second conduit.

80. A liquid cooling system as set forth in claim 77, wherein an output cavity is disposed in the heat exchange system.

81. A liquid cooling system as set forth in claim 80, wherein a pump is disposed in the output cavity, the pump pumping the cooled liquid, wherein the step of transporting the cooled liquid on the second conduit is performed in response to the pump pumping the cooled liquid.

82. A liquid cooling system as set forth in claim 77, further comprising an airflow device for directing air from within the casing over the heat dissipater and out of the casing.

83. A liquid cooling system as set forth in claim 74, further comprising, a heat exchange system coupled to the second conduit, the heat exchange system further comprising, a heat dissipater generating cooled liquid in response to receiving the liquid, a liquid cavity housing the cooled liquid, and a fan positioned between the heat dissipater and the liquid cavity the fan causing air flow over the heat dissipater and the liquid cavity.

84. A liquid cooling system as set forth in claim 83, wherein the heat dissipater further comprises a liquid tube positioned within the heat dissipater, the liquid tube conveying the liquid through the heat dissipater to generate the cooled liquid.

85. A liquid cooling system as set forth in claim 83, further comprising a pump coupled to the liquid cavity, the pump performing the step of transporting the cooled liquid on the second conduit.

86. A liquid cooling system comprising:
a circuit board capable of receiving a processor generating heat;
a heat conducting material deployed within the circuit board and receiving the heat from the processor; and
a conduit coupled to the heat conducting material, the conduit dissipating heat in the heat conducting material by transporting liquid through the conduit.

87. A liquid cooling system as set forth in claim 86, wherein the liquid is cooled liquid.

88. Liquid cooling system as set forth in claim 86, further comprising, a heat exchange system coupled to the conduit, the heat exchange system receiving the liquid transported on the conduit and generating cooled liquid.

89. A liquid cooling system as set forth in claim 88, wherein an input cavity is disposed in the heat exchange system, the input cavity receiving the liquid transported on the conduit.

90. A liquid cooling system as set forth in claim 88, wherein a dissipater is disposed in the heat exchange system, the dissipater generating cooled liquid in response to receiving the liquid transported on the conduit.

91. A liquid cooling system as set forth in claim 88, wherein an output cavity is disposed in the heat exchange system.

92. A liquid cooling system as set forth in claim 91, wherein a pump is disposed in the output cavity, the pump pumping the cooled liquid, wherein the step of transporting the cooled liquid on the second conduit is performed in response to the pump pumping the cooled liquid.

93. A liquid cooling system as set forth in claim 93, wherein the liquid cooling system is disposed in a casing, the liquid cooling system further comprising a heat exchange system including a heat dissipater in liquid communication with the conduit;

a liquid cavity in liquid communication with the heat dissipater for storing cooled liquid; and

a pump disposed within the liquid cavity for circulating liquid through the system.

94. A liquid cooling system as set forth in claim 93, further comprising an airflow device for directing air from within the casing over the heat dissipater and out of the casing.

95. A liquid cooling system as set forth in claim 86, further comprising, a heat exchange system coupled to the conduit, the heat exchange system further comprising, a heat dissipater generating cooled liquid in response to receiving the liquid, a liquid cavity housing the cooled liquid, and a fan positioned between the heat dissipater and the liquid cavity the fan causing air flow over the heat dissipater and the liquid cavity.

96. A liquid cooling system as set forth in claim 95, wherein the heat dissipater further comprises a liquid tube positioned within the heat dissipater, the liquid tube conveying the liquid through the heat dissipater to generate the cooled liquid.

97. A liquid cooling system as set forth in claim 95, further comprising a pump coupled to the liquid cavity, the liquid tube conveying the liquid through the heat dissipater in response to the pump pumping the liquid through the liquid cavity.

98. A liquid cooling system comprising:
a circuit board capable of receiving a processor generating heat;
a heat conducting material deployed within the circuit board and receiving the heat from the processor, the heat conducting material forming a cavity, the cavity providing a conduit for liquid to flow through the cavity, the liquid dissipating the heat;
an input conduit coupled to the cavity, the input conduit providing an entry point for the liquid; and
an output conduit coupled to the cavity, the output conduit providing an exit point for the liquid.

99. Liquid cooling system as set forth in claim 98, further comprising,

a heat exchange system coupled to the input conduit and coupled to the output conduit, the heat exchange system receiving heated liquid from the output conduit and transporting cooled liquid to the input conduit.

100. A liquid cooling system as set forth in claim 99, wherein an input cavity is disposed in the heat exchange system, the input cavity receiving the liquid transported on the output conduit.

101. A liquid cooling system as set forth in claim 99, wherein a dissipater is disposed in the heat exchange system, the dissipater generating cooled liquid in response to receiving the liquid transported on the output conduit.

102. A liquid cooling system as set forth in claim 99, wherein an output cavity is disposed in the heat exchange system.

103. A liquid cooling system as set forth in claim 102, wherein a pump is disposed in the output cavity, the pump pumping the cooled liquid.

104. A liquid cooling system as set forth in claim 98, wherein the liquid cooling system is disposed in a casing, the liquid cooling system further comprising a heat exchange system including a heat dissipater in liquid communication with the input conduit and with the output conduit;

a liquid cavity in liquid communication with the heat dissipater for storing cooled liquid; and

a pump disposed within the liquid cavity for circulating the cooled liquid through the system.

105. A liquid cooling system as set forth in claim 106, further comprising an airflow device for directing air from within the casing over the heat dissipater and out of the casing.

106. A liquid cooling system as set forth in claim 98, further comprising,

a heat exchange system coupled to the conduit, the heat exchange system further comprising, a heat dissipater generating cooled liquid in response to receiving the heated liquid, a liquid cavity housing the cooled liquid, and a fan positioned between the heat dissipater and the liquid cavity the fan causing air flow over the heat dissipater and the liquid cavity.

107. A liquid cooling system as set forth in claim 106, wherein the heat dissipater further comprises a liquid tube positioned within the heat dissipater, the liquid tube conveying the heated liquid through the heat dissipater to generate the cooled liquid.

108. A liquid cooling system as set forth in claim 106, further comprising a pump coupled to the liquid cavity, the pump performing the step of transporting cooled liquid on the input conduit.

109. A liquid cooling system comprising:

a housing means;

a receptacle means disposed in the housing means, the receptacle means for mating with packaging material means associated with a processor to form a cavity, the processor generating heat;

an inlet means disposed in the housing means, the inlet means for receiving liquid, the liquid flowing through the cavity and removing the heat by flowing across the packaging material means; and

an outlet means disposed in the housing means, the outlet means for providing an exit point for the liquid flowing through the cavity.

110. A liquid cooling system comprising:

a housing means;

a receptacle means disposed in the housing means, the receptacle means for mating with packaging means associated with a processor to form a cavity, the processor generating heat;

a pump means disposed in the cavity, the pumping means for pumping liquid through the cavity;

an inlet means disposed in the housing means, the inlet means for receiving the liquid in response to the pump means pumping the liquid through the cavity, the liquid flowing through the cavity and removing the heat by making contact with the packaging means; and

an outlet means disposed in the housing, the outlet means for outputting the liquid in response to the pump means pumping the liquid through the cavity.

111. A liquid cooling system comprising:

a first conduit means for transporting first liquid;

a first heat transfer means coupled to the first conduit means, the heat transfer means for mating with a processor on a first side, the processor generating heat, the first heat transfer capable of dissipating the heat by conveying the first liquid through the first heat transfer;

a second heat transfer means coupled to the first conduit means, the second heat transfer means for mating with the processor on a second side, the second heat transfer system capable of further dissipating the heat by conveying the first liquid through the second heat transfer means; and

a second conduit means coupled to the first heat transfer system means and coupled to the second heat transfer system means, the second

conduit means for transporting second liquid in response to conveying the first liquid through the first heat transfer system means and in response to conveying first liquid through the second heat transfer system means.

112. A liquid cooling system comprising:

a first housing means comprising a receptacle means for mating with first packaging material associated with a processor, to form a first cavity, the processor generating heat;

a second housing means comprising a receptacle means for mating with second packaging material associated with the processor, to form a second cavity;

a first inlet means disposed in the first housing means, the first inlet means for receiving first liquid, the liquid flowing through the first cavity and removing the heat by making contact with the first packaging material;

a second inlet means disposed in the second housing means, the second inlet means for receiving second liquid, the second liquid flowing through the second cavity and removing the heat by making contact with the second packaging material;

a first outlet means disposed in the first housing means, the first outlet means for providing an exit point for the first liquid flowing through the first cavity; and

a second outlet means disposed in the second housing means, the second outlet means for providing an exit point for the second liquid flowing through the second cavity.

113. A liquid cooling system comprising:

a first conduit means transporting first liquid;

a first heat transfer means coupled to the first conduit means, the first heat transfer means for mating with a first processor on a first side, the first processor generating first heat, the first heat transfer means capable of

dissipating the first heat by conveying the first liquid through the first heat transfer means;

a second heat transfer means coupled to the first conduit means, the second heat transfer means for mating with the first processor on a second side and a second processor on a first side, the second heat transfer means capable of further dissipating the first heat by conveying the first liquid through the second heat transfer means and the second heat transfer means capable of dissipating the second heat by conveying the first liquid through the second heat transfer means;

a third heat transfer means coupled to the first conduit means, the second heat transfer means for mating with the second processor on a second side, the third heat transfer means capable of further dissipating the second heat by conveying the first liquid through the third heat transfer means;

a second conduit means coupled to the first heat transfer means, coupled to the second heat transfer means and coupled to the third heat transfer means, the second conduit means transporting second liquid in response to conveying the first liquid through the first heat transfer means, in response to conveying first liquid through the second heat transfer means and in response to conveying first liquid through the third heat transfer means.

114. A liquid cooling system comprising:

a first housing means comprising a first receptacle means for mating with first packaging material associated with a first processor, to form a first cavity, the first processor generating first heat;

a second housing means comprising a second receptacle means for mating with second packaging material associated with the first processor and comprising a third receptacle means for mating with third packaging material associated with a second processor, to form a second cavity, the second processor generating second heat;

a third housing means comprising a fourth receptacle means for mating with fourth packaging material associated with the second processor, to form a third cavity;

a first inlet means disposed in the first housing means, the first inlet means for receiving first liquid, the first liquid flowing through the first cavity and dissipating the first heat by making contact with the first packaging material;

a second inlet means disposed in the second housing means, the second inlet means for receiving second liquid, the second liquid flowing through the second cavity and dissipating the first heat by making contact with the second packaging material, the second liquid flowing through the second cavity and dissipating the second heat by making contact with the third packaging material;

a third inlet means disposed in the third housing means, the third inlet means for receiving third liquid, the third liquid flowing through the third cavity and removing the second heat by making contact with the fourth packaging material;

a first outlet means disposed in the first housing means, the first outlet means for providing an exit point for the first liquid flowing through the first cavity;

a second outlet means disposed in the second housing means, the second outlet means for providing an exit point for the second liquid flowing through the second cavity; and

a third outlet means disposed in the third housing means, the third outlet means for providing an exit point for the third liquid flowing through the third cavity.

115. A liquid cooling system comprising:

a first conduit means for transporting liquid;

a cavity means coupled to the first conduit means, the cavity means for mating with packaging material deployed on multiple sides of a processor, the processor generating heat, the cavity conveying the liquid in response to transporting the liquid on the first conduit means, the liquid dissipating the heat; and

a second conduit means coupled to the cavity, the second conduit means for transporting liquid in response to the cavity conveying the liquid.

116. A liquid cooling system comprising:

a circuit board means for coupling with a processor generating heat;

a heat conducting means deployed within the circuit board means, the heat conducting means for receiving the heat from the processor; and

a conduit means coupled to the heat conducting means, the conduit means for dissipating heat in the heat conducting means by transporting liquid through the conduit means.

117. A liquid cooling system comprising:

a circuit board means capable of receiving a processor generating heat;

a heat conducting means deployed within the circuit board means and receiving the heat from the processor, the heat conducting means for forming a cavity, the cavity providing a conduit for liquid to flow through the cavity, the liquid dissipating the heat;

an input conduit means coupled to the cavity, the input conduit means for providing an entry point for the liquid; and

an output conduit means coupled to the cavity, the output conduit means for providing an exit point for the liquid.